

Gate Driver Unit 2DU180506MR03

■Overview

2DU180506MR03 is a dual channel gate driver designed for Rohm's SiC power module BSM080D12P2C008.

Built-in isolated DC / DC converter and gate drive circuit, in addition, gate resistor and short circuit detection voltage have already been set.

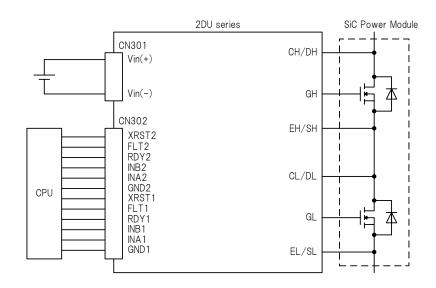
■Features

- ·Ideal for drive of SiC Power module BSM080D12P2C008(ROHM)
- ·Gate resistor : $10\Omega(TYP)$
- ·Short circuit detection voltage: 7.0V(TYP)
- ·Constitution : Gate driver module (2DM180506CM) + PCB for power module connection
- · ALL-IN-ONE (Built-in isolated DC / DC converter and gate drive circuit)
- ·Ideal for half bridge operation with dual output
- \cdot Optimum gate voltage for driving SiC-MOSFET(+18V/-5V) / BSM080D12P2C008(ROHM)
- ·Low parasitic capacitance (about 15pF); highly resistant to common-mode noise.
- ·Fast response : 100nsec(typ)
- •The gate drive circuit used a magnetic isolator.
- ·Dielectric withstand voltage: AC2500V (1 second guarantee)
- ·Insulation distance (clearance / creepage): 6mm/6mm
- ·DC/DC converter input voltage: 15~24V
- ·Signal input voltage: 5V
- ·Overload protection (DC/DC converter)
- ·Overheat protection (DC/DC converter)
- ·Desaturation protection (Gate drive circuit)
- ·Fault signal output function (Gate drive circuit)
- ·Miller clamp function (Gate drive circuit)
- ·Under-voltage lockout(UVLO) (Gate drive circuit)
- ·Filling structure

■ Application

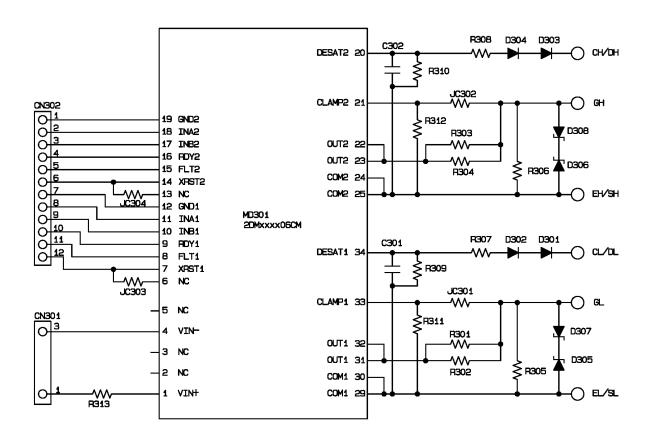
Industrial inverter, PV inverter, etc...

■Ciruit Image





■Circuit Diagram



■Pin Connection

CN301: B2(3)B-EH(JST) For power supply

Pin No.	Name	Function						
1	Vin(+)	Power supply for DC/DC converter(+)						
2	N.C.	Unused						
3	Vin(-)	Power supply for DC/DC converter(-)						

CN302: B12B-ZR-SM4-TF(JST) For signal

Pin No.	Name	CH	Function			
1	GND2	2(H)	Ground for control circuit			
2	INA2	2(H)	Control input A			
3	INB2	2(H)	Control input B			
4	RDY2	2(H)	Ready output			
5	FLT2	2(H)	Fault output			
6	XRST2	2(H)	Reset input			
7	GND1	1(L)	Ground for control circuit			
8	INA1	1(L)	Control input A			
9	INB1	1(L)	Control input B			
10	RDY1	1(L)	Ready output			
11	FLT1	1(L)	Fault output			
12	XRST1	1(L)	Reset input			

Connection on the power module

Name	СН	Explanation of pins					
CL/DL	1(L)	Drain connection, Low side *					
GL	1(L)	Gate connection, Low side					
EL/SL	1(L)	Source connection, Low side					
CH/DH	2(H)	Drain connection, High side *					
GH	2(H)	Gate connection, High side					
EH/SH	2(H)	Source connection, High side					

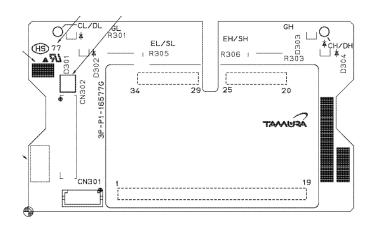
^{*} Connect to each drain terminal with a lead wire or the like.

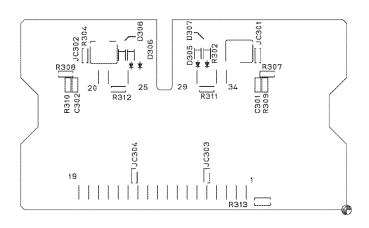


■Parts list

Symbol	Description	Part No.	Manufacturer	Remark
D301-304	Diode	CMF05	TOSHIBA	Or equivalent
D305-308	Diode	OPEN		SOD-323
C301,302	Capacitor	OPEN		SMD1608
R301-304	Resistor	20 Ω J		SMD3264
R305,306	Resistor	47kΩJ		SMD1608
R307,308	Resistor	1.8k Ω J		SMD1608
R309-312	Resistor	OPEN		SMD1608
R313	Resistor	0 Ω		SMD2125
JC301,302	Jumper	0Ω		SMD1608
JC303,304	Jumper	OPEN		SMD1608
CN301	Connector	B2(3)B-EH	JST	
CN302	Connector	B12B-ZR-SM4-TF	JST	
MD301	Gate Driver Module	2DM180506CM	TAMURA	

■Mouting Drawing





Parts side Solder side



■I/O Condition Table

No.	Status				Input					Out	put	
INO.	Status	V_{5VDC}	V_{OUTH}	DESAT	XRST	INB	INA	CLAMP	OUT	CLAMP	FLT	RDY
1		0	UVLO	L	Χ	Χ	Χ	Н	L	Hi-Z	Н	L
2	V _{OUTH} UVLO	0	UVLO	L	Χ	Χ	Χ	L	L	L	Н	L
3	VOUTH OVEO	0	UVLO	Н	Χ	Χ	Χ	Н	L	Hi-Z	L	L
4		0	UVLO	Η	Χ	Χ	Χ	L	L	L	L	L
5	DESAT	0	0	Н	Χ	Χ	Χ	Н	L	Hi-Z	L	H(*)
6	DLOAT	0	0	Η	Χ	Χ	Χ	L	L	L	L	H(*)
7	XRST	0	0	L	L	Χ	Χ	Н	L	Hi-Z	Η	H(*)
8	ANGT	0	0	L	L	Χ	Χ	L	L	L	Н	H(*)
9		0	0	L	Н	Η	Χ	Н	L	Hi-Z	Η	H(*)
10		0	0	L	Н	Н	Χ	L	L	L	Н	H(*)
11	Normal operation	0	0	L	Н	L	L	Н	L	Hi-Z	Η	H(*)
12		0	0	L	Н	L	L	L	L	L	Н	H(*)
13		0	0	L	Н	L	Н	Χ	Н	Hi-Z	Н	H(*)

O:5VDC or OUT(H) UVLO > UVLO, X:Don't care

■ Absolute Maximum Ratings

lte	em	Symbol	Min	Max	Unit	Conditions · Note
Input voltage for DC/DC converter		V _{IN}	-0.3	28	Vdc	Between Vin(+) to Vin(-)
Input-side signal voltage		V_{SG}	-0.3	5.2	V	INA, INB, XRST, RDY, FLT
Maximum gate charg	e	Q_{G}	_	390	nC	
Switching frequency	Ta=55°C	F _{sw}	_	200	kHz	Test load : 3.0 Ω / 16.5nF
Switching frequency	Ta=85°C	F _{sw}	-	80	kHz	1621 load : 2.0 32 / 10.5111
Short circuit detection	n pin voltage	V_{SD}	0	1000	V	
Maximum gate currer	nt	I _{GPEAK}	-1.8	1.8	Α	Guaranteed by design
Input-side signal max	imum current	I _{SG}	_	5	mA	RDY, FLT
Operating temperatur	re range	T _{OP}	-40	85	$^{\circ}$ C	See the derating curve
Operating humidity		RH _{OP}	20	95	%RH	No condensation
Storage temperature range		T_{STG}	-40	100	$^{\circ}$ C	
Storage humidity		RH _{STG}	5	95	%RH	No condensation

■Recommended Operating Conditons

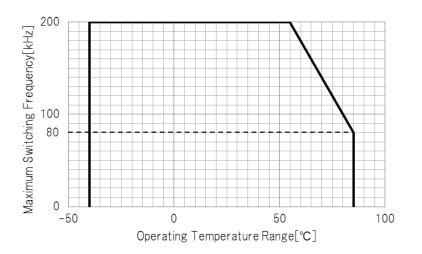
ltem	Symbol	Min	Max	Unit	Conditions · Note
Input voltage range for DC/DC converter	V_{IN}	13.5	26.4	Vdc	
Driver circuit number	N	_	2	_	
Logic high level input voltage	V_{SGH}	2	5	V	INA, INB ,XRST
Logic low level input voltage	V_{SGL}	0	0.8	V	INA, INB ,XRST
Source current of control signal	I _{SG}	20	_	mA	INA, INB, XRST, V _{SG} =5V
Minimum input pulse width	t _{INMSK}	1	60	ns	

^(*) If the internal logic of high voltage side doesn't become the expected value, the RDY pin will become "L". And this stage is cleared automatically if the internal logic of high voltage side becomes the expected value.



■ Ambient Temperature Derating Curve

Reduce the switching frequency according to the following temperature derating table.



■Electrical Specification (Vin=24V, Ta=25°C, Unless otherwise specified)

DC/DC converter block

ltem	Symbol	Min	Тур	Max	Unit	Conditions · Note
Start-up voltage	V _{START}	-	11.5	12.5	V	
Efficiency	Effi	69	74	_	%	I _{OUTAVE} (CH1,2):100mA
Standby power	P _{STBY}	-	0.7	1	W	No load
Output voltage(Hgih)	V ₁₊ ,V ₂₊	17.5	18.5	19.5	V	$I_{OUTAVE}(CH1) = I_{OUTAVE}(CH2) = 10-130mA$
Output Voltage(rigili)	v ₁₊ , v ₂₊	17.5	18.5	20.5	V	$I_{OUTAVE}(CH1) = I_{OUTAVE}(CH2) = 0-10mA$
Output voltage(Low)	V ₁₋ ,V ₂₋	-6	-5	-4	V	$I_{OUTAVE}(CH1) = I_{OUTAVE}(CH2) = 0-130mA$
Output Voltage(High)(Load imbalance)	V ₁₊ ,V ₂₊	-	-	25	V	I _{OUTAVE} (CH1):100mA,I _{OUTAVE} (CH2):0mA
Output Voltage(Low)(Load imbalance)	V ₁₋ ,V ₂₋	-10	-	-	V	or I _{OUTAVE} (CH1):0mA,I _{OUTAVE} (CH2):100mA

Gate drive block

	ltem	Symbol	Min	Тур	Max	Unit	Conditions · Note
Logic							
Logic high leve	l input voltage	V_{SGH}	2	-	5.2	V	INA, INB ,XRST
Logic low level	input voltage	V_{SGL}	0	-	0.8	V	INA, INB ,XRST
Logic pull-dow	n resistance	R_{SGD}	_	270	-	Ω	INA, INB ,XRST
Logic pull-up r	esistance	R _{sgu}	ı	5100	ı	Ω	RDY, FLT
Logic input ma	sk time	t _{INMSK}	-	_	60	ns	INA, INB
Minimum XRST	pulse width	t _{XRSTMIN}	800	_	_	ns	
Output							
Output pin volt	age(Hgih)	V _{OUTH}	_	V _{DCDCOH} -0.5	_	V	No load
Output pin volt	age(Low)	V _{OUTL}	1	V _{DCDCOL} +0.1	ı	V	No load
Gate resistor		Rg	ı	10	-	Ω	
CLAMP ON res	istance	R _{ONPRO}	0.2	0.5	0.9	Ω	I _{CLAMP} =40mA
Low level CLA	MP current	I _{CLAMPL}	3	4.5	_	А	Guaranteed by design
CLAMP ON thr	eshold voltage	V_{CLPON}	V _{OUTL} +1.8	V _{OUTL} +2	V _{OUTL} +2.2	V	Guaranteed by design
Delay time	Turn ON time	t _{PON}	50	90	130	ns	
Delay LIIIIe	Turn OFF time	t _{POFF}	50	90	130	ns	



■Protection

DC/DC converter block

ltem	Symbol	Min	Тур	Max	Unit	Conditions · Note
Overload protection	_	6	_	_	W	Auto recovery
Overheat protection	-	120	-	150	°C	Internal temperature

Gate drive block

Item	Symbol	Min	Тур	Max	Unit	Conditions · Note
OUT(H) UVLO OFF voltage	V_{UVLOOHH}	11.3	12.3	13.3	V	Guaranteed by design
OUT(H) UVLO ON voltage	$V_{\rm UVLOOHL}$	10.3	11.3	12.3	V	Guaranteed by design
Short circuit detection voltage	V_{SD}	_	7	-	V	Guaranteed by design
DESAT filter time	t _{DESATFIL}	0.16	0.25	0.34	us	Guaranteed by design
DESAT delay time(OUT)	t _{DESATOUT}	0.31	0.38	0.45	us	Guaranteed by design
DESAT delay time(FLT)	t_{DESATFLT}	0.34	0.42	0.5	us	Guaranteed by design
DESAT low voltage	V_{DESATL}	ı	0.1	0.22	V	I _{DESAT} =1mA
DESAT leading edge blanking	t _{DESTLEB}	0.28	0.4	0.52	us	Guaranteed by design
RDY output low voltage	V_{RDYL}	_	0.08	0.15	V	I _{RDY} =5mA
FLT output low voltage	V_{FLTL}	_	0.08	0.15	V	I _{FLT} =5mA

■Insulation

ltem	Specification	Conditions · Note
Between Input-Output	•	<u> </u>
Dielectric withstand voltage	AC2500V	1min, Cutoff 2mA
Test dielectric withstand voltage	AC2500V	1sec, Cutoff 2mA
Insulation resistance	100MΩ or more	DC500V
Minimum clearance distances	6mm MIN	
Minimum creepage distances	6mm MIN	
Between Ch1-Ch2	•	
Dielectric withstand voltage	None	
Test dielectric withstand voltage	None	
Insulation resistance	None	
Minimum clearance distances	5.5mm MIN	
Minimum creepage distances	5.5mm MIN	



■Pin Function

- ·Vin(+), Vin(-) (Power supply pin for DC/DC converter)
- •GND(Ground pin for drive curcuit)
- ·INA, INB, XRST(Control input pin, XRST input pin)

The INA, INB and XRST pin is a pin used to determine output logic.

And, holding of the fault signal is canceled by rising of $L \to H$ of the XRST pin input signal.

XRST	INB	INA	OUT
L	Χ	Χ	L
Н	Н	Χ	L
Н	L	L	L
Н	L	Н	Н

·FLT(Fault output pin)

The FLT pin is an open drain pin used to output a fault signal when desaturation function is activated, and will be cleared at the rising edge of FLT.

Status		
While in normal operation		
When desaturation function is activated		

·RDY(Ready output pin)

The RDY pin shows the status of three internal protection features which are 5VDC UVLO, OUT(H) UVLO, and output state feedback (OSFB). The term 'output state feedback' shows whether output internal logic is high or low corresponds to input logic or not.

Status		
While in normal operation		
5VDC UVLO or OUT(H) UVLO or Output internal logic feedback		

·CL/DL(Low side MOSFET Drain connection pin)

CL/DL is a land to be connected to the low side MOSFET drain of the power device.

•GL(Low side MOSFET Gate connection pin)

GL is a land to be connected to the low side MOSFET gate of the power device.

·EL/SL(Low side MOSFET Source connection pin)

EL/SL is a land to be connected to the low side MOSFET source of the power device.

·CH/DH(High side MOSFET Drain connection pin)

CH/DH is a land to be connected to the high side MOSFET drain of the power device.

·GH(High side MOSFET Gate connection pin)

GH is a land to be connected to the high side MOSFET gate of the power device.

•EH/SH(Low side MOSFET Source connection pin)

EH/SH is a land to be connected to the high side MOSFET source of the power device.

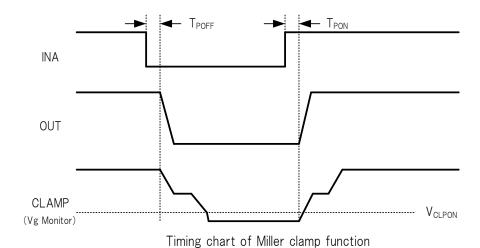


■Description Of Protection

1. Gate voltage rise prevention function

If OUT=L and the CLAMP pin voltage < VCLPON, the internal MOSFET of the CLAMP pin turns on.

OUT	CLAMP	Internal MOSFET of the CLAMP pin
L	Less than V _{CLPON}	ON
L	Not less than V _{CLPON}	OFF
Н	X	OFF



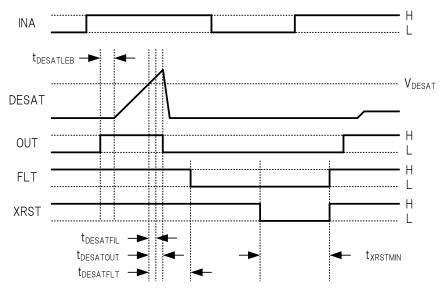
2. Undervoltage Lockout (UVLO) function

The control circuit incorporates the undervoltage lockout (UVLO) function both on the OUT(H) sides. When the OUT(H) voltage drops to the UVLO ON voltage, the OUT pin and the RDY pin both will output the "L"signal. When the OUT(H) voltage rises to the UVLO OFF voltage, these pins will be reset. To prevent malfunctions due to noises, mask time t_{UVLO1MSK} and t_{UVLO2MSK} are set on both input and output sides.

3. Desaturation protection function(DESAT), Fault signal output function

When the DESAT pin voltage exceeds VDESAT, the DESAT function will be activated.

When the DESAT function is activated, the OUT pin voltage will be set to the "L" level, and then the FLT pin voltage to the "L" level. When the rising edge is put in the XRST pin, the DESAT function will be released.



DESAT Operation Timing Chart



■Reliability

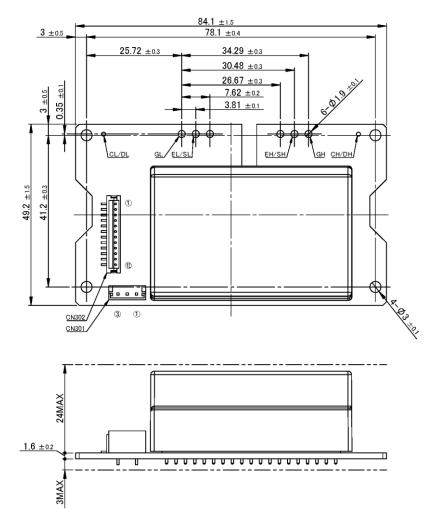
ltem	Test condition and acceptance criterion		
Exposure in high temperature	100°C, 240H, ※		
Exposure in low temperature	-40°C, 240H, ※		
Exposure in high temperature and high humidity	60°C, 90∼95%RH, 240H, ※		
Thermal shock	-40°C/30min to 100°C/30min, 500cycles, ※		
Low temperature operation	Input voltage:DC24V, Output current:Rated Load		
	-40°C, 240H, ※		
High temperature operation	Input voltage:DC24V, Output current:Rated Load		
	85°C, 240H, ※		
high temperature	Input voltage:DC24V, Output current:Rated Load		
and high humidity operation	60°C, 90∼95%RH, 240H, ※		
Vibration	Vibration amplitude:1.5mm(peak to peak), Vibration Frequency:10 to 55Hz, Sweeping:1min.		
	In each X, Y and Z direction: once, 120min. ※		
Impact	Acceleration:490m/s² (50G), Operating time:11ms		
	In each $\pm X$, Y and Z direction:3 times, $ imes$		
Drop test for packaged freights	Dorp to concrete. Height: 40cm		
	Dorp surface: 1 corner, 3 spines, 6 surfaces, 1 time each.		

XAfter each test, exposure at room temperature and humidity condition for 24 hours.

There shall be no abnormality on the electrical specification and appearance.



■Outline Dimensional Drawing



Unit:mm

Note :1.The dimensional tolerance without directions is \pm 0.5mm.

■Product Weight

89g(TYP)



■Recommended Soldering Condition

·Soldering condition of hand work : 350°C(MAX) Less than 4sec

■Storage Conditions

ltem	Min	Max	Unit	Conditions · Note
Storage temperature	-25	60	$^{\circ}$ C	A packing state

^{*}If you want to use past the long period there is a concern that the solder non-wetting by terminal oxidation to occur.

Therefore, please use from taking enough tests.

■Usage Cautions

- Always mount fuse on the plus side of input for ensuring safety because the fuse is not built-in the product. Please select the fuse considering conditions such as steady current, inrush current, and ambient temperature. When using a fuse having large rated current or high capacity input electrolytic condenser, by combining another converter and input line and input electrolytic condenser, fuse may not blow off in the case of abnormality. Do not combine high voltage line and fuse.
- This product is designed to be best when it drives two devices to have the same gate capacitance simultaneously.

 Because it leads to the "output unstable" and "output accuracy deterioration".

 If you want to use to drive only one of the devices, because of the output voltage accuracy deterioration prevention, please configure the dummy gate circuit (resistor and capacitor) to consume the equivalent of the power and the drive side.
- This product is to transmit the signal of the insulating part by the magnetic coupling.
 Therefore, if you use this product in a strong magnetic field in, there is a possibility of malfunction.
 In that case, connect the capacitor between the GND terminal of this product and a metal enclosure.
- Make sure the rise/fall time of the input signal is 500ns or less.
- Please confirm with the device supplier for the detail such as the screw type, material, torque force that tighten to device.



■Important Notice

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 - Use in liquids such as water, oil, chemical solutions, or organic solvents, and use in locations where the product will be exposed to such liquids.
 - · Use that involves exposure to direct sunlight, outdoor exposure, or dusty conditions.
 - · Use in locations where corrosive gases such as salt air, C12, H2S, NH3, S02, or NO2, are present.
 - · Use in environments with strong static electricity or electromagnetic radiation.
 - · Use that involves placing inflammable material next to the product.
 - · Use of this product either sealed with a resin filling or coated with resin.
 - · Use of water or a water soluble detergent for flux cleaning.
 - \cdot $\,$ Use in locations where condensation is liable to occur.
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